

TECHNICAL REPORT



**Surface mounting technology –
Part 3-1: Standard method for the specification of components for through hole
reflow (THR) soldering – Guidelines for through hole diameter design with solder
paste surface printing method**

INTERNATIONAL
ELECTROTECHNICAL
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A list of all parts in the IEC 61760 series, published under the general title *Surface mounting technology*, can be found on the IEC website.

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SURFACE MOUNTING TECHNOLOGY –

Part 3-1: Standard method for the specification of components for through hole reflow (THR) soldering – Guidelines for through hole diameter design with solder paste surface printing method

1 Scope

This Part of IEC 61760 supplements IEC 61760-3 to describe examples of solder paste supply methods, the relationship between the terminal position tolerance and the through hole diameter, and provides guidelines for the design of printed circuit boards with solder paste surface printing method, including specific examples.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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